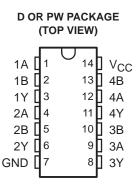
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- Controlled Baseline
 One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- [†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering informatiom

- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17



The SN74ALVC00 quadruple 2-input positive-NAND gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The device performs the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING				
4000 10 0500	SOIC – D	Tape and reel	SN74ALVC00IDREP	ALVC00IEP				
–40°C to 85°C	TSSOP – PW	Tape and reel	SN74ALVC00IPWREP§	ALVC00E				

ORDERING INFORMATION

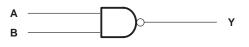
[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

§ Product Preview

FUNCTION TABLE (each gate)					
INP	UTS	OUTPUT			
Α	В	Y			

	013	OUTPUT
Α	В	Y
Н	Н	L
L	Х	Н
Х	L	Н

logic diagram, each gate (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 4.6 V
Output voltage range, V _O (see Notes 1 and 2)	-0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} (V _O < 0)	
Continuous output current, IO	
Continuous current through V _{CC} or GND	
Package thermal impedance, θ_{JA} (see Note 3): D package	
	113°C/W
Storage temperature range, T _{stg}	
resses beyond those listed under "absolute maximum ratings" may cause permanent damage to the d	device. These are stress ratings only, and

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 4.6 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
VIH	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
		V_{CC} = 2.7 V to 3.6 V	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
VIL	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
		V_{CC} = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	3.6	V
VO	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
	High-level output current	V _{CC} = 2.3 V		-12	
юн		V _{CC} = 2.7 V		-12	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		12	•
IOL	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			5	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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PARAMETER	TEST CON	IDITIONS	V _{CC}	MIN	TYP [†]	MAX	UNIT
	I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2				
	$I_{OH} = -6 \text{ mA}$		2.3 V	2			
VOH			2.3 V	1.7			V
-	$I_{OH} = -12 \text{ mA}$		2.7 V	2.2			
		3 V	2.4				
	I _{OH} = -24 mA		3 V	2			
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2		
	I _{OL} = 4 mA	1.65 V			0.45		
	I _{OL} = 6 mA		2.3 V			0.4	.,
V _{OL}		2.3 V			0.7	V	
	I _{OL} = 12 mA	2.7 V			0.4		
	I _{OL} = 24 mA	3 V			0.55		
lj –	$V_{I} = V_{CC}$ or GND		3.6 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			10	μΑ
ΔICC	One input at V _{CC} – 0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μΑ
Ci	$V_{I} = V_{CC}$ or GND		3.3 V		4.5		pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CC} = ± 0.1		۷ _{CC} = ± 0.2		V _{CC} =	2.7 V	۲ <mark>0.3 V_{CC} =</mark>		UNIT
	(INPUT)	(INPUT) (OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	1	4.4	1	2.8		3.2	0.5	3	ns

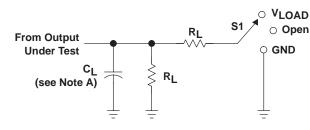
operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS		V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	UNIT
Cpd	Power dissipation capacitance per gate	$C_{L} = 0,$	f = 10 MHz	20	21	23	pF



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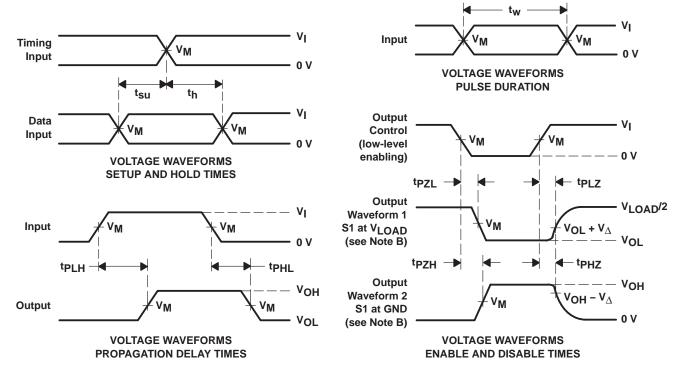




LOAD CIRCUIT

TEST	S1
^t pd	Open
^t PLZ ^{/t} PZL	V _{LOAD}
^t PHZ ^{/t} PZH	GND

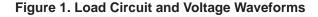
No. a	IN	PUT			0	D.	N
Vcc	VI	t _r /t _f	Vм	VLOAD	CL	RL	v_Δ
1.8 V \pm 0.15 V	Vcc	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$\textbf{2.5}\pm\textbf{0.2}~\textbf{V}$	Vcc	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.

- D. The outputs are measured one at a time, with one transition per measurement.
- D. The outputs are measured one at a time,
- E. tpLz and tpHz are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALVC00IDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04685-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74ALVC00-EP :

- Catalog: SN74ALVC00
- Automotive: SN74ALVC00-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVC00IDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

5-Nov-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ALVC00IDREP	SOIC	D	14	2500	333.2	345.9	28.6	

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



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